

Dual N-channel MOSFET

KFCAB22020NL Datasheet

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1. GENERAL DESCRIPTION

Gate resistor installed Dual N-channel MOSFET for lithium-ion secondary battery protection circuits.

2. FEATURES

- Source-source On-state Resistance: RSS(on) typ = $1.90 \text{ m}\Omega \text{ (VGS} = 3.8 \text{ V)}$
- CSP (Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1)

3. MARKING SYMBOL: RL

4. PACKAGING

Embossed type (Thermo-compression sealing): 8,000 pcs / reel (standard)

5. ABSOLUTE MAXIMUM RATINGS Ta = $25 \degree C$

Parameter		Symbol	Rating	Unit	
Source-source Voltage		VSS	22	V	
Gate-source Voltage		VGS	± 12	V	
	DC *1	IS1	15.3		
Source Current	DC *2	IS2	27.5	А	
	DC *3	IS3	37.2		
	Pulsed *4	ISp	153		
	DC *1	PD1	0.59		
Total Power Dissipation	DC *2	PD2	1.9	W	
	DC *3	PD3	3.5		
Operating Junction and Storage Temperature Range		Tj, Tstg	- 55 to + 150	°C	



Parameter	Symbol	Rating	Unit	
	Rth1 *1	212		
Thermal Resistance (ch-a)	Rth2 ^{*2}	66	°C / W	
	Rth3 *3	36		

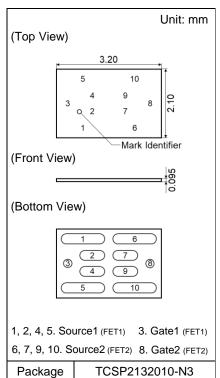
Note *1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).

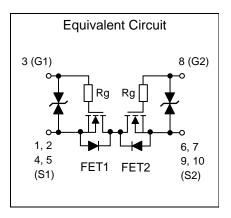
FR4 board partially covered with copper pad (42 mm² area, 36 µm thickness).
*2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).

FR4 board fully covered with copper pad (605 mm² area, 36 μ m thickness).

*3 Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).

*4 t = 10 $\mu s, \, Duty \, Cycle \leq$ 1 %.



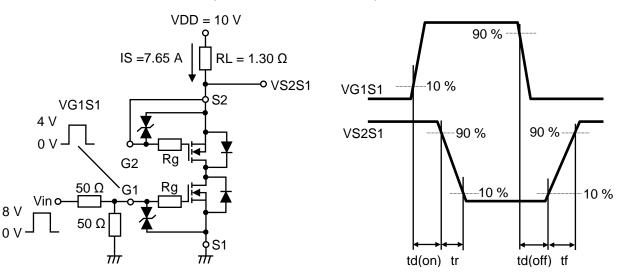


7. ELECTRICAL CHARACTERISTICS Ta = $25 \degree C \pm 3 \degree C$

Parameter	Symbol	Conditions	Min	Тур	Мах	Unit	
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	22			V	
Zero Gate Voltage Source Current	ISSS	VSS = 22 V, VGS = 0 V			1	μA	
	IGSS1	$VGS = \pm 8 V, VSS = 0 V$			± 10	μA	
Gate-source Leakage Current	IGSS2	VGS = ± 5 V, VSS = 0 V			± 1		
Gate-source Threshold Voltage	Vth	IS = 1.21 mA, VSS = 10 V	0.35	0.90	1.40	V	
	RSS(on)1	IS = 7.65 A, VGS = 4.5 V	1.20	1.80	2.35		
Source course On state Resistance	RSS(on)2	IS = 7.65 A, VGS = 3.8 V	1.25	1.90	2.50		
Source-source On-state Resistance	RSS(on)3	IS = 7.65 A, VGS = 3.1 V	1.30	2.05	3.30	mΩ	
	RSS(on)4	IS = 7.65 A, VGS = 2.5 V	1.40	2.40	5.25		
Body Diode Forward Voltage	VF(s-s)	IF = 7.65 A, VGS = 0 V		0.7	1.0	V	
Input Capacitance *1	Ciss			7500			
Output Capacitance *1	Coss	VSS = 10 V, VGS = 0 V, f = 1 kHz		570		pF	
Reverse Transfer Capacitance *1	Crss			520			
Turn-on Delay Time *1, *2	td(on)	VDD = 10 V, VGS = 0 to 4 V		40			
Rise Time ^{*1, *2}	tr	IS = 7.65 A		200		ns	
Turn-off Delay Time *1, *2	td(off)	VDD = 10 V, VGS = 4 to 0 V		740			
Fall Time ^{*1, *2}	tf	IS = 7.65 A		320		ns	
Total Gate Charge ^{*1}	Qg	VDD = 10 V		67			
Gate-source Charge *1	Qgs	VGS = 0 to 4 V		13		nC	
Gate-drain Charge *1	Qgd	IS = 15.3 A		14			
Gate Resistance *1	Rg	f = 1 MHz	4	9	17	Ω	

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors. *1 Guaranteed by design, not subject to production testing.

*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time.

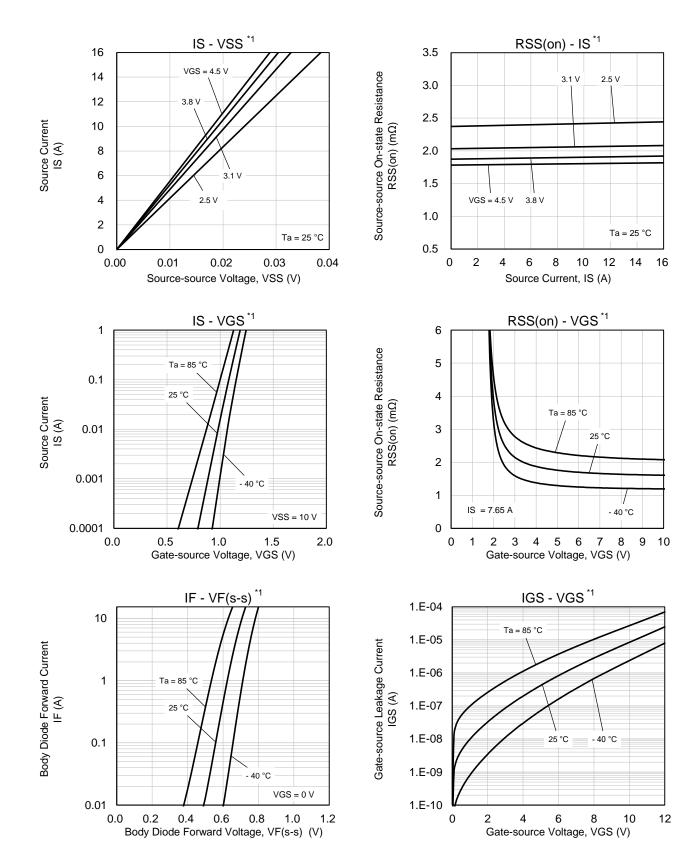


8. ELECTROSTATIC DISCHARGE CHARACTERISTIC Ta = 25 °C ± 3 °C

Standard	Test Type	Symbol	Conditions	Class	Value	Unit
AEC-Q101-001	Human Body Model	HBM	$C = 100 \text{ pF}, \text{ R} = 1.5 \text{ k}\Omega$	H2	$> 2k$ to $\le 4k$	V

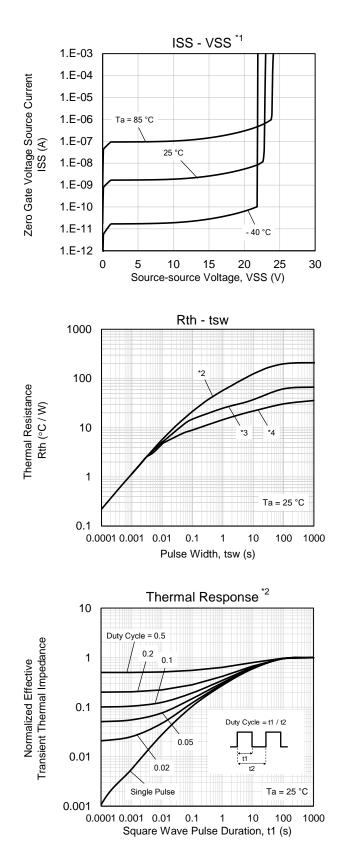
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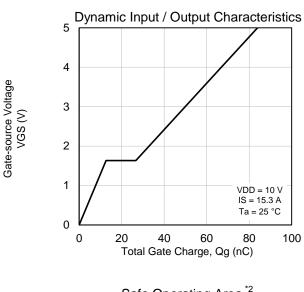
9. TECHNICAL DATA (Reference)

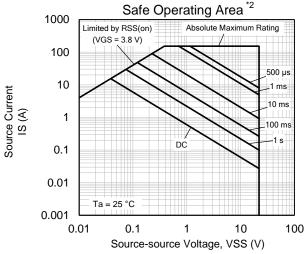


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TECHNICAL DATA (Reference)







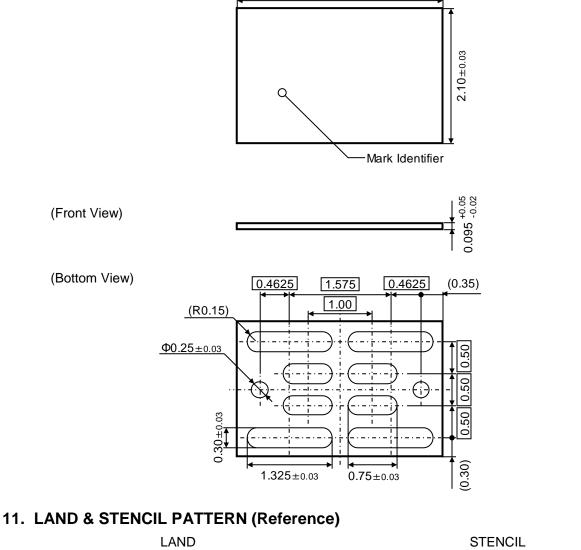
Note

- *1 Pulse measurement.
- *2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
 FR4 board partially covered with copper pad (42 mm² area, 36 µm thickness).
- *3 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm). FR4 board fully covered with copper pad (605 mm² area, 36 μm thickness).
- *4 Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).

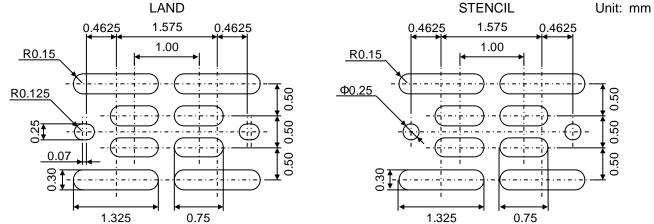
Unit: mm

10. OUTLINE

(Top View)



3.20±0.03



Important notice:

Solder Mask Defined (SMD) pattern is strongly recommended for pad design. Please check the information in the Nuvoton WL-CSP Application Notes about mounting process.

12. REVISION HISTORY

2022.5.16 2022.9.15	1.00	1. Initially issued.
2022.9.15		
	2.00	1. Revised ESD class.
2022.12.23	3.00	1. Revised ESD class.
		2. Revised the value of Rg.
		3. Revised the value of Ciss, Coss, Crss to TBD.
		4. Revised the value of td(on), tr, td(off), tf to TBD.
		5. Added important notice in Land Pattern.
2023.3.6	4.00	1. Updated the value of Ciss, Coss, Crss
		2. Updated the value of td(on), tr, td(off)

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